Power MOSFET

100 V, 15 m Ω , 50 A, Single N-Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	100	V
Gate-to-Source Voltage	Gate-to-Source Voltage			±20	V
Continuous Drain	Steady	T _C = 25°C	I _D	50	Α
Current R _{θJC} (Notes 1, 2, 3)		T _C = 100°C		32	
Power Dissipation	State	$T_C = 25^{\circ}C$	P_{D}	77	W
R _{θJC} (Notes 1, 2)		T _C = 100°C		32	
Continuous Drain		$T_A = 25^{\circ}C$	I _D	10	Α
Current R _{θJA} (Notes 1, 2, 3)	Steady	T _A = 100°C		6.4	
Power Dissipation	State	T _A = 25°C	P _D	3.1	W
R _{θJA} (Notes 1 & 2)		T _A = 100°C		1.3	
Pulsed Drain Current	$T_A = 25^\circ$	°C, t _p = 10 μs	I _{DM}	180	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to + 150	°C
Source Current (Body Diode)			IS	60	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 24 A)			E _{AS}	29	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit	
Junction-to-Case - Steady State	$R_{\theta JC}$	1.6	°C/W	
Junction-to-Ambient - Steady State (Note 2)	$R_{ heta JA}$	40		

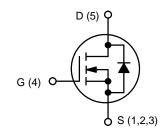
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



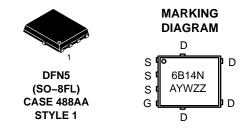
ON Semiconductor®

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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
100 V	15 mΩ @ 10 V	50 A



N-CHANNEL MOSFET



A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS					<u> </u>		1
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		100			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				80		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	T _J = 25 °C			10	μΑ
		V _{DS} = 80 V	T _J = 125°C			100	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = 20 V				100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 250 \mu A$		2.0		4.0	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-8.5		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 20 A		12.2	15	mΩ
		V _{GS} = 6 V	I _D = 10 A		18.5	23	mΩ
CHARGES, CAPACITANCES & GATE RESI	STANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 50 V			1300		pF
Output Capacitance	C _{OSS}				260		
Reverse Transfer Capacitance	C _{RSS}				18		
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 10 \text{ V}, V_{DS} = 50 \text{ V}; I_D = 20 \text{ A}$ $T_J = 25 \text{ °C}$			20		nC
Threshold Gate Charge	Q _{G(TH)}				2.2		
Gate-to-Source Charge	Q_GS				6.4		
Gate-to-Drain Charge	Q_GD				6.5		
Plateau Voltage	V_{GP}				5.4		V
Gate Resistance	R_{G}				1.0		Ω
SWITCHING CHARACTERISTICS (Note 5)							
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = 10 \text{ V}, V_{DS} = 50 \text{ V},$ $I_{D} = 20 \text{ A}, R_{G} = 1.0 \Omega$			9.6		ns
Rise Time	t _r				39		
Turn-Off Delay Time	t _{d(OFF)}				17		
Fall Time	t _f				6.8		
DRAIN-SOURCE DIODE CHARACTERISTI	cs						
Forward Diode Voltage	V _{SD}	$V_{GS} = 0 \text{ V},$ $I_{S} = 20 \text{ A}$	$T_J = 25^{\circ}C$		0.83	1.2	.,
			T _J = 125°C		0.8		V
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 100 \text{ A}/\mu\text{s,}$ $I_{S} = 20 \text{ A}$			45		ns
Charge Time	ta				23		
	1 .				22		
Discharge Time	t_b	.5 =07	li di		22		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$.

5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

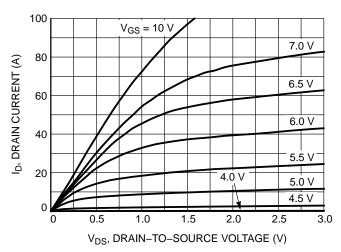


Figure 1. On-Region Characteristics

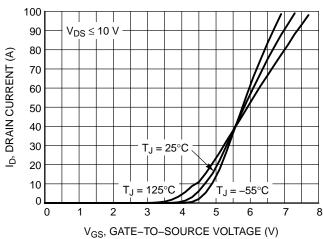


Figure 2. Transfer Characteristics

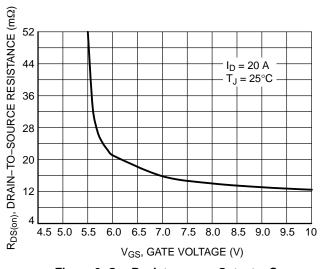


Figure 3. On–Resistance vs. Gate–to–Source Voltage

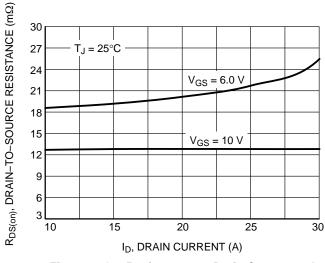


Figure 4. On–Resistance vs. Drain Current and Gate Voltage

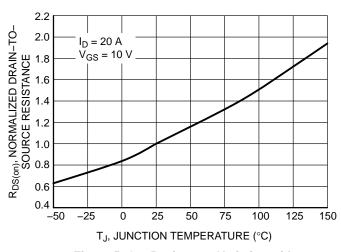


Figure 5. On–Resistance Variation with Temperature

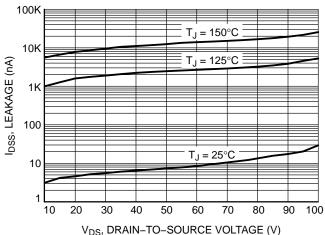


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

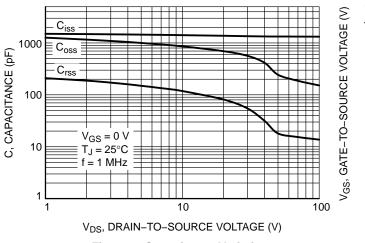


Figure 7. Capacitance Variation

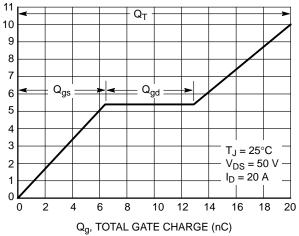


Figure 8. Gate–to–Source and

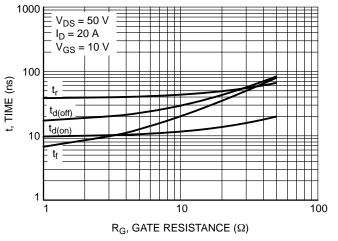


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

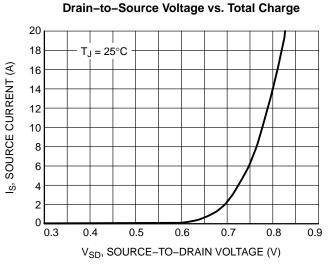
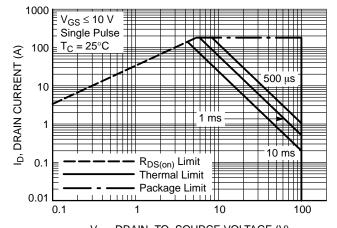


Figure 10. Diode Forward Voltage vs. Current



 $\mathsf{V}_\mathsf{DS}, \mathsf{DRAIN}\text{-}\mathsf{TO}\text{-}\mathsf{SOURCE}\;\mathsf{VOLTAGE}\;(\mathsf{V})$

Figure 11. Maximum Rated Forward Biased Safe Operating Area

TYPICAL CHARACTERISTICS

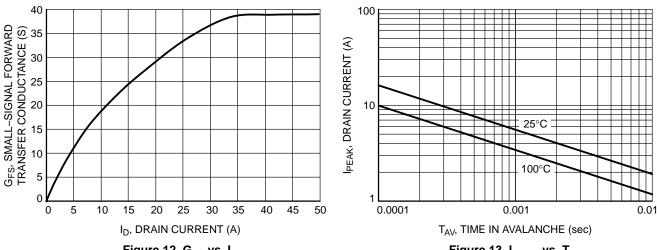


Figure 12. G_{FS} vs. I_D

Figure 13. I_{PEAK} vs. T_{AV}

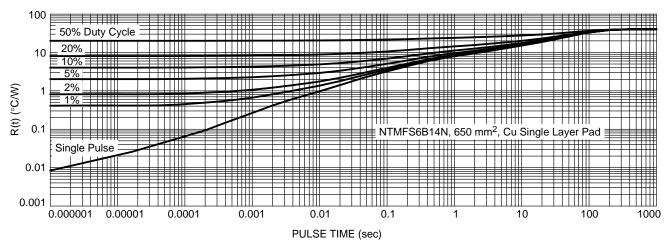


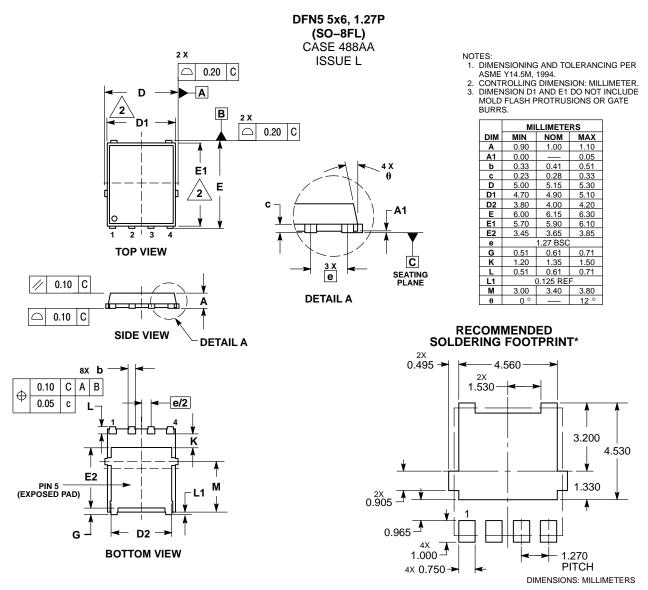
Figure 14. Thermal Response

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTMFS6B14NT1G	6B14N	DFN5 (Pb-Free)	1500 / Tape & Reel
NTMFS6B14NT3G	6B14N	DFN5 (Pb-Free)	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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